FOR LOW FREQUENCY POWER AMPLIFY APPLICATION SILICON PNP EPITAXIAL TYPE

DESCRIPTION

2SB1035 is a resin sealed silicon PNP epitaxial type transistor. It is designed for low frequency power amplify application.

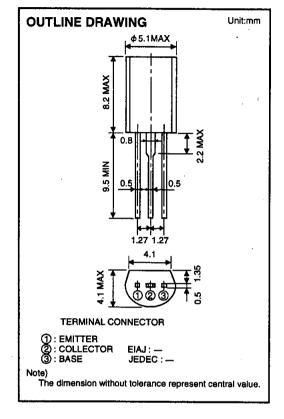
Complementary with 2SD1447.

FEATURE

- ●High collector current Icм=-1.5A
- ●High gain band width product fr=100MHz typ
- ●High collector dissipation Pc=900mW
- Excellent linearity of DC forward current gain

APPLICATION

Radio,tape recorder,small type stereo,etc. Low frequency power amplify circuit with 2 to 3.5W output.



MAXIMUM RATINGS (Ta=25℃)

Symbol	Parameter	Ratings	Unit
Vcво	Collector to Base voltage	-30	V
VEBO	Emitter to Base voltage	-4	V
VCEQ	Collector to Emitter voltage	-25	V
Ісм	Peak collector current	-1.5	Α
lc ·	Collector current	-1	Α
Pc	Collector dissipation(Ta=25℃)	900	mW
Tj	Junction temperature	+150	ో
Tstg	Storage temperature	-55 to +150	ార

ELECTRICAL CHARACTERISTICS (Ta=25°C)

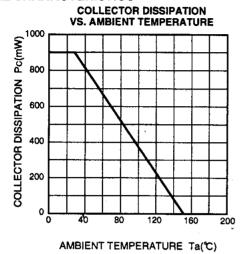
Symbol	Parameter	Test conditions		Limits		
			Min	Тур	Max	Unit
V(BR)CBO	C to B break down voltage	Ic=-10 μ A,Iε=0	-30			V
V(BR)EBO	E to B break down voltage	IE=-10 μ A,IC=0	-4			V
V(BR)CEO	C to E break down voltage	lc=-100 μ A,R8E=∞	-25			V
Ісво	Collector cut off current	VcB=-25V,IE=0			-1	μΑ
IEBO	Emitter cut off current	VEB=-2V,IC=0			-1	μΑ
hfE *	DC forward current gain	VcE=-1V,lc=-500mA	55		300	-
VCE(sat)	C to E saturation voltage	lc=-500mA,lB=-25mA			-0.5	V
fr	Gain band width product	VcE=-6V,IE=10mA		100		MHz

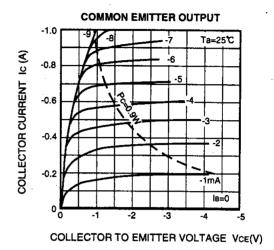
^{* :} It shows here classification in right table.

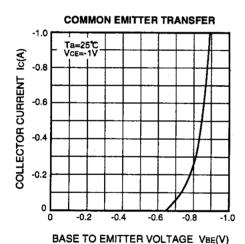
hFE 55	to 110 9	90 to 180	150 to 300

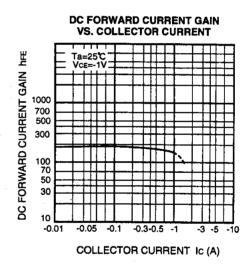
FOR LOW FREQUENCY POWER AMPLIFY APPLICATION SILICON PNP EPITAXIAL TYPE

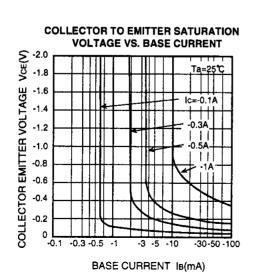
TYPICAL CHARACTERISTICS













http://www.idc-com.co.jp 6-41, TSUKUBA, ISAHAYA, NAGASAKI, 854-0065, JAPAN

Keep safety in your circuit designs!

Isahaya Electronics Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

•These materials are intended as reference to assist out customers in the selection of the Isahaya semiconductor product best suited to the customer's application, they do not convey any license under any intellectual property rights, or any other rights, belonging to Isahaya Electronics Corporation or a third party.

Isahaya Electronics Corporation assumes no responsibility for any damage, or infringement of any third-party rights, originating in the use of any product data, diagrams, charts or circuit application examples contained in the materials.

All information contained in these materials, including product data, diagrams and charts, represent information on products at the time of publication of these materials, and are subject to change by Isahaya Electronics Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Isahaya Electronics Corporation or authorized Isahaya Semiconductor product distributor for the latest product information before purchasing a product listed herein.

The prior written approval of Isahaya Electronics Corporation is necessary to reprint or reproduce in whole or in part these materials.

If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination. Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.

Please contact Isahaya Electronics Corporation or an authorized Isahaya Semiconductor product distributor for further details on these materials or the products contained therein.